

# Call for Papers



Le Méridien Hotel Kuala Lumpur, Malaysia. 4-5 November 2024

2024 IEEE Industrial Electronics and Applications Conference (IEACon 2024) will be held at Kuala Lumpur, Malaysia, on 4 to 5 November 2024. This is the 5<sup>th</sup> edition of IEACon, which is organized by IEEE Malaysia Industrial Electronics (IE) / Industrial Applications (IA) Joint Chapter. The conference is technically co-sponsored by the IEEE Industry Applications Society. The objectives of the conference are to provide high quality research and professional interactions for the advancement of science, technology, and fellowship. IEACon 2024 program will feature keynotes, technical paper presentations and technical exhibitions. Prospective authors are invited to electronically submit full papers in English, in pdf format following instructions accessible via <https://ieeieacon.org/>. Accepted and presented papers will be submitted for inclusion in the IEEE Xplore online digital library and EI Compendex database. Authors of selected papers (20% out of total number of papers in this conference) will be invited to submit extended versions of their manuscripts for consideration in the IEEE Transactions on Industry Applications (Q1 Journal) and IEEE IAS Magazine.

## TRACKS

The scope of the IEEE IEACon2024 includes all scope items of the IEEE Industry Applications Society and includes all scope items of the IEEE Industry Electronics Society.

- Cloud Computing, Big Data and Software Engineering
- Control Systems, Robotics and Mechatronics
- Electrical Machines and Drives
- Electronic Systems on Chip and Embedded Control
- Industrial Automation, Communication, Networking, and Informatics
- Industrial Electronics and Education
- Power Electronics
- Power Systems and Smart Grids
- Renewable Energy
- Sensors, Actuators and Micro-Nanotechnology
- Signal and Image Processing and Computational Intelligence

## CONFERENCE FEES

Registration Type	Fees	
	USD	RM
IEEE Member	470	1800
Non-IEEE Member	570	2200
Student (IEEE Member)*	400	1500
Student (Non-IEEE Member)*	450	1700
Non-Author IEEE Member	400	1500
Non-Author Non-IEEE Member	450	1700
Full Registration	745	3200

### Note:

- Registered fees include admission to all conference sessions, daily lunch, tea breaks and conference kit.
- The full registration fee includes two nights' accommodation at Le Meridien Hotel Kuala Lumpur (check-in date: November 3, 2024, and check-out date: November 5, 2024).

Organizer:



IEEE Malaysia IE/IA Joint Chapter

Technical Co-Sponsor:



## IMPORTANT DATES

Submission of Full Paper Deadline

**5 June 2024**

Notification of Paper Acceptance

**5 August 2024**

Normal Registration Deadline

**3 October 2024**

Final Camera Ready Deadline

**3 October 2024**

Conference Dates

**4-5 November 2024**

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Conference website:

<https://ieeieacon.org/>



Paper Submission Link:

<https://edas.info/N31638>



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